

# EPIGAP Optronik GmbH

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## Product Data Sheet

### LED Chip Infra Red

### EOLC-905-17

Rev. 01 aus 2011

Radiation	Type	Electrodes
Infrared	DDH	P (anode) up

	typ. dimension (μm) typ. thickness 150 ± 25 μm anode gold alloy 1.5μm cathode gold alloy 0.5μm structured, 25% covered
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### Optical and Electrical Characteristics

T<sub>amb</sub> = 25°C, unless otherwise specified

Parameter	Test cond.	Symbol	Min	Typ	Max	Unit
Forward voltage	I <sub>F</sub> =20mA	V <sub>F</sub>		1.3	1.5	V
Reverse voltage	I <sub>R</sub> =100μA	V <sub>R</sub>	5			V
Radiant Power <sup>1</sup>	I <sub>F</sub> =20mA	Φ <sub>e</sub>	3.0	4.0		mW
Radiant Power <sup>2</sup>	I <sub>F</sub> =20mA	Φ <sub>e</sub>		8.0		mW
Switching time	I <sub>F</sub> =20mA	t <sub>r</sub> , t <sub>f</sub>		400		ns
Peak wavelength	I <sub>F</sub> =20mA	λ <sub>p</sub>	895	905	915	nm
Spectral bandwidth at 50%	I <sub>F</sub> =20mA	Δλ <sub>0.5</sub>		55		nm

<sup>1</sup>Power measurement on bare chip on gold plate

<sup>2</sup>Power measurement on epoxy covered chip on TO-18 header

### Labeling

Type	Lot N°	Φ <sub>e</sub> (typ) [mW]	V <sub>F</sub> (typ) [V]	Quantity
EOLC-905-17				

### Packing

Chips on adhesive film with wire-bond side top